

# 0.8A, 200V - 1000V High Efficient Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

### **MECHANICAL DATA**

• Case: SOD-123W

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

• Polarity: Indicated by cathode band

• Weight: 0.016g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
l <sub>F</sub>	0.8	Α	
$V_{RRM}$	200 - 1000	٧	
I <sub>FSM</sub>	20	Α	
T <sub>J MAX</sub>	150	°C	
Package	SOD-123W		
Configuration	Single die		







**SOD-123W** 



DADAMETER	CVMDOL	HSD	HSG	HSJ	HSK	HSM	
PARAMETER	SYMBOL	LWH	LWH	LWH	LWH	LWH	UNIT
Marking code on the device		HSDLW	HSGLW	HSJLW	HSKLW	HSMLW	
Repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	140	280	420	560	700	V
Forward current	I <sub>F</sub>			0.8			Α
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	20		А			
Junction temperature	$T_J$	- 55 to +150			°C		
Storage temperature	T <sub>STG</sub>	- 55 to +150			°C		

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	34	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	86	°C/W	
Junction-to-case thermal resistance	$R_{ heta JC}$	35	°C/W	

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		$I_F = 0.4A, T_J = 25^{\circ}C$		0.81	0.97	V
		I <sub>F</sub> = 0.8A, T <sub>J</sub> = 25°C		0.86	1.00	V
	HSDLWH	I <sub>F</sub> = 0.4A, T <sub>J</sub> = 125°C		0.66	0.79	V
		I <sub>F</sub> = 0.8A, T <sub>J</sub> = 125°C		0.73	0.83	V
		$I_F = 0.4A, T_J = 25$ °C		0.84	1.01	V
(1)		I <sub>F</sub> = 0.8A, T <sub>J</sub> = 25°C	=	0.91	1.30	V
Forward voltage <sup>(1)</sup>	HSGLWH	I <sub>F</sub> = 0.4A, T <sub>J</sub> = 125°C	$V_{F}$	0.70	0.83	V
		I <sub>F</sub> = 0.8A, T <sub>J</sub> = 125°C	=	0.77	1.05	V
		I <sub>F</sub> = 0.4A, T <sub>J</sub> = 25°C		1.17	1.40	V
	HSJLWH	I <sub>F</sub> = 0.8A, T <sub>J</sub> = 25°C		1.31	1.70	V
	HSKLWH	I <sub>F</sub> = 0.4A, T <sub>J</sub> = 125°C		0.93	1.12	V
	HSMLWH	I <sub>F</sub> = 0.8A, T <sub>J</sub> = 125°C		1.09	1.30	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 25°C		-	1	μΑ
		T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	150	μA
HSDLWH				17	-	pF
	HSGLWH		Сл	14	-	pF
Junction capacitance	HSJLWH	1MHz, V <sub>R</sub> = 4.0V				
	HSKLWH			5	-	pF
	HSMLWH					
	HSDLWH		t <sub>rr</sub>		50	
	HSGLWH			-	50	ns
Reverse recovery time	HSJLWH	$I_F = 0.5A$ , $I_R = 1.0A$				
	HSKLWH	$I_{rr} = 0.25A$		-	75	ns
	HSMLWH					

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup> PACKAGE PACKING				
HSxLWH	SOD-123W	10,000 / Tape & Reel		

### Notes:

1. "x" defines voltage from 200V(HSDLWH) to 1000V(HSMLWH)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

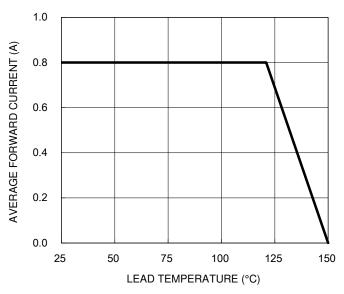


Fig.2 Typical Junction Capacitance

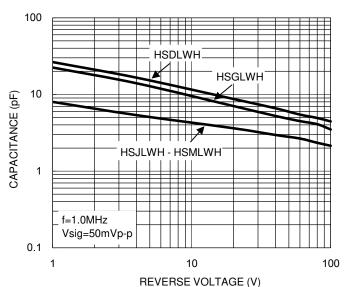
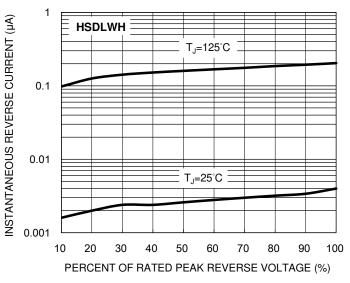
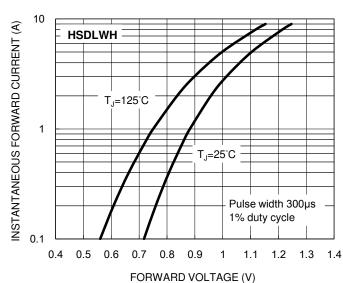


Fig.3 Typical Reverse Characteristics



**Fig.4 Typical Forward Characteristics** 

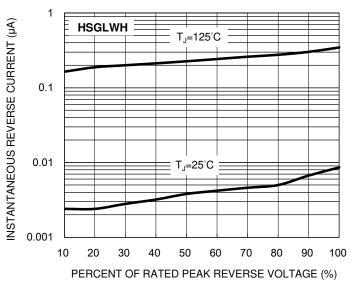




## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.5 Typical Reverse Characteristics



**Fig.6 Typical Forward Characteristics** 

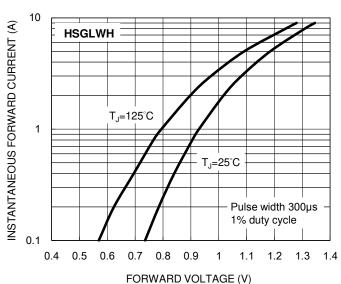


Fig.7 Typical Reverse Characteristics

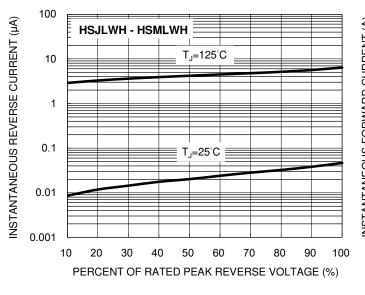
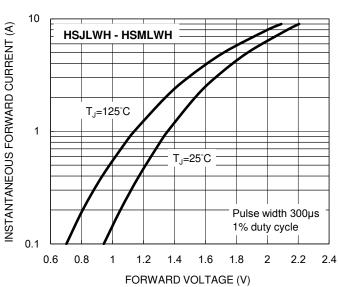
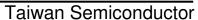


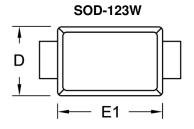
Fig.8 Typical Forward Characteristics

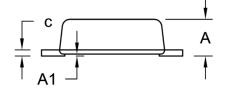


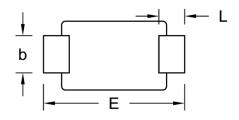




## **PACKAGE OUTLINE DIMENSIONS**

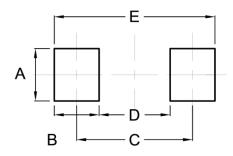






DIM.	Unit (mm)		Unit (inch)	
DIIVI.	Min.	Max.	Min.	Max.
Α	0.90	1.02	0.035	0.040
A1	0.00	0.10	0.000	0.004
b	0.90	1.05	0.035	0.041
С	0.10	0.22	0.004	0.009
D	1.70	1.90	0.067	0.075
E	3.60	3.80	0.142	0.150
E1	2.60	2.90	0.102	0.114
L	0.50	0.85	0.020	0.033

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

# **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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